MOSFETs Silicon Carbide N-Channel MOS

TW083Z65C

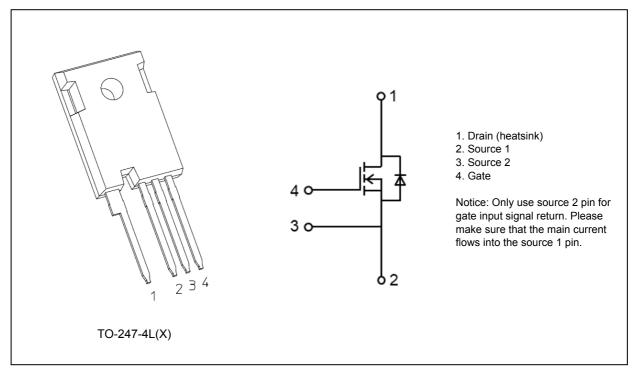
1. Applications

• Switching Voltage Regulators

2. Features

- (1) Chip design of 3rd generation (Built-in SiC schottky barrier diode)
- (2) Low diode forward voltage: V_{DSF} = -1.35 V (typ.)
- (3) High voltage: $V_{DSS} = 650 \text{ V}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 83 \text{ m}\Omega$ (typ.)
- (5) Less susceptible to malfunction due to high threshold voltage: V_{th} = 3.0 to 5.0 V (V_{DS} = 10 V, I_D = 0.6 mA)
- (6) Recommended gate source drive voltage: $V_{GS_{on}} = 18 \text{ V}, V_{GS_{off}} = 0 \text{ V}$
- (7) Enhancement mode.

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note)

(T_a = 25 °C unless otherwise specified)

| CI | naracteristics | Symbol | Rating | Unit | |
|------------------------|----------------------------|----------|------------------|------------|-------|
| Drain-source voltage | | | V _{DSS} | 650 | V |
| Gate-source voltage | | | V _{GSS} | +25/-10 | |
| Drain current (DC) | (T _c = 25 °C) | (Note 1) | Ι _D | 30 | Α |
| Drain current (DC) | (T _c = 100°C) | (Note 1) | Ι _D | 21 | |
| Drain current (pulsed) | (T _c = 25 °C) | (Note 1) | I _{DP} | 66 | |
| Drain current (pulsed) | (T _c = 100°C) | (Note 1) | I _{DP} | 52 | 7 |
| Power dissipation | (T _c = 25°C) | | PD | 111 | W |
| Channel temperature | | | T _{ch} | 175 | °C |
| Storage temperature | | | T _{stg} | -55 to 175 | |
| Mounting torque | | | TOR | 0.8 | N · m |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|---------------------------------------|-----------------------|-------|------|
| Channel-to-case thermal resistance | R _{th(ch-c)} | 1.350 | °C/W |
| Channel-to-ambient thermal resistance | R _{th(ch-a)} | 50 | |

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care. It should be used for switching applications.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

| Characteristics | | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-----------------------------------|----------|----------------------|--|-----|------|------|------|
| Gate leakage current | | I _{GSS} | V _{GS} = +25/-10 V, V _{DS} = 0 V | | _ | ±0.1 | μA |
| Drain cut-off current | | I _{DSS} | V _{DS} = 650 V, V _{GS} = 0 V | | 3 | 37 | |
| | | | T _a = 150 °C, V _{DS} = 650 V, V _{GS} = 0 V | — | 14 | — | |
| Drain-source breakdown voltage | | V _{(BR)DSS} | I _D = 4 mA, V _{GS} = 0 V | 650 | | _ | V |
| Gate threshold voltage | (Note 2) | V _{th} | V _{DS} = 10 V, I _D = 0.6 mA | 3.0 | _ | 5.0 | |
| Drain-source on-resistance | | R _{DS(ON)} | V _{GS} = 18 V, I _D = 15 A | — | 83 | 118 | mΩ |
| | | | T _a = 150 °C, V _{GS} = 18 V, I _D = 15 A | _ | 89 | _ | |

Note 2: Please be sure to apply I_{GSS} (V_{GS} = 25 V) before the V_{th} test.

6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|---------------------|---|-----|------|-----|------|
| Input capacitance | C _{iss} | V _{DS} = 400 V, V _{GS} = 0 V, | _ | 873 | _ | pF |
| Reverse transfer capacitance | C _{rss} | f = 100 kHz | | 3.4 | _ | |
| Output capacitance | C _{oss} | 1 | _ | 110 | _ | |
| Effective output capacitance (energy related) | C _{o(er)} | | — | 125 | — | |
| Effective output capacitance (time related) | C _{o(tr)} | | — | 180 | — | |
| Output charge | Q _{oss} | | | 72 | _ | nC |
| C _{oss} stored energy | E _{oss} | 1 | _ | 10 | _ | μJ |
| Gate resistance | r _g | V _{DS} = OPEN, f = 1 MHz | | 4.4 | _ | Ω |
| Turn-on delay time | t _{d(on)} | See Fig. 6.2.1 | _ | 21 | _ | ns |
| Switching time (rise time) | tr | 7 | _ | 14 | _ | 1 |
| Turn-off delay time | t _{d(off)} | | | 28 | | 1 |
| Switching time (fall time) | t _f | | _ | 14 | _ | |
| Turn-on switching loss | Eon | 7 | | 98 | | μJ |
| Turn-off switching loss | E _{off} | 7 | _ | 38 | _ | |

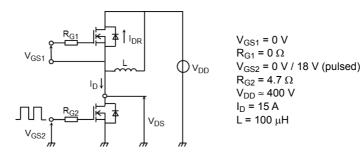


Fig. 6.2.1 Switching Time Test Circuit

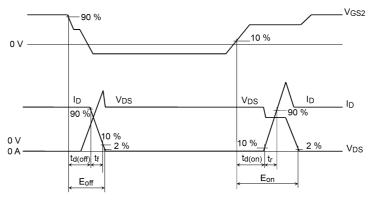


Fig. 6.2.2 Timing Diagrams

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

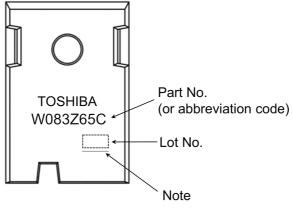
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg | $V_{DD} \approx 400 \text{ V}, \text{ V}_{GS} = 18 \text{ V},$ I_D = 15 A | — | 28 | — | nC |
| Gate-source charge 1 | Q _{gs1} | | _ | 14 | — | |
| Gate-drain charge | Q _{gd} | | | 3.9 | _ | |

6.4. Source \cdot Drain Characteristics (T_a = 25 °C unless otherwise specified)

| Characteristics | | Symbol | Test Condition | Min | Тур. | Max | Unit |
|----------------------------------|----------|------------------|---|-----|-------|-------|------|
| Reverse drain current (DC) | (Note 3) | I _{DR} | T _c = 25 °C, V _{GS} = -5 V | _ | _ | 26 | А |
| | | | T _c = 100 °C, V _{GS} = -5 V | | | 17 | |
| | | | T _c = 25 °C, V _{GS} = 18 V | _ | — | 30 | |
| | | | T _c = 100 °C, V _{GS} = 18 V | | _ | 21 | |
| Reverse drain current | (Note 3) | I _{DRP} | T _c = 25 °C, V _{GS} = -5 V | | | 66 | |
| (pulsed) | | | T _c = 100 °C, V _{GS} = -5 V | _ | _ | 29 | |
| | | | T _c = 25 °C, V _{GS} = 18 V | | _ | 66 | |
| | | | T _c = 100 °C, V _{GS} = 18 V | | | 52 | |
| Diode forward voltage | | V _{DSF} | I _{DR} = 8 A, V _{GS} = -5 V | | -1.35 | -1.80 | V |
| | | | T _a = 150 °C, I _{DR} = 8 A, V _{GS} = -5 V | — | -1.57 | _ | |
| Reverse recovery time | | t _{rr} | I _{DR} = 10 A, V _{GS} = 0 V, | | 45 | _ | ns |
| Reverse recovery charge | | Q _{rr} | V _{DD} = 400 V, -dI _{DR} /dt = 1000 A/μs | _ | 189 | _ | nC |
| Peak reverse recovery current | | I _{rr} | | — | 8.4 | — | A |

Note 3: Ensure that the channel temperature does not exceed 175 °C.

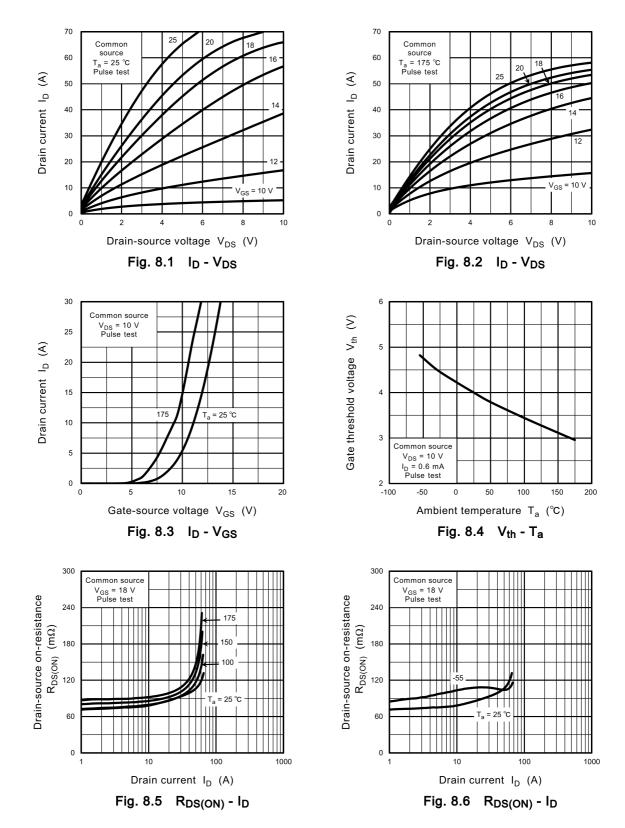
7. Marking (Note)



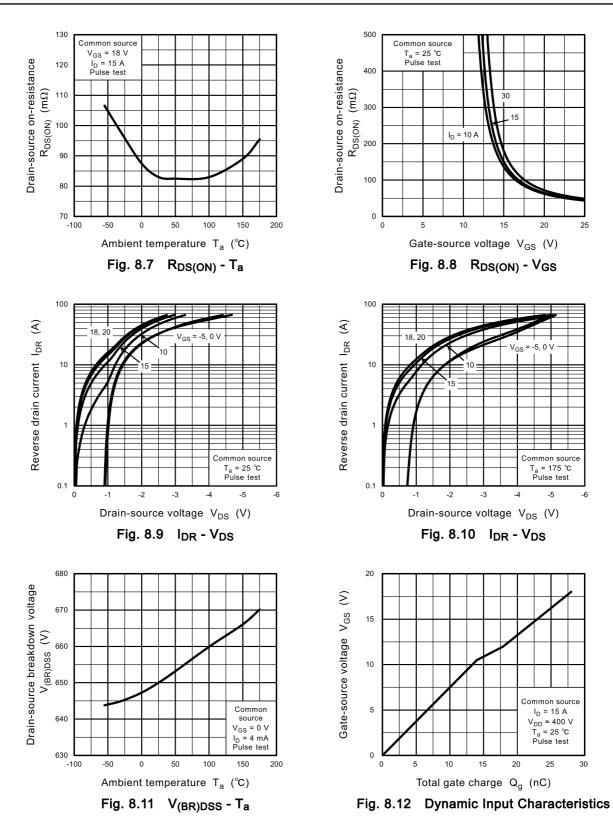


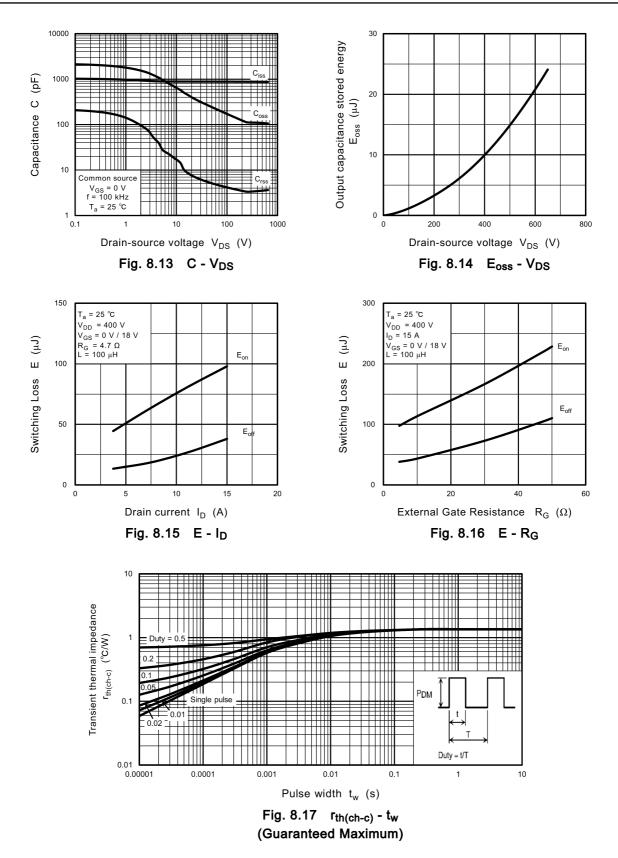
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8. Characteristics Curves (Note)

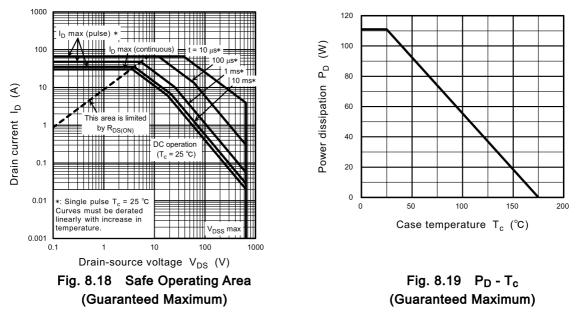


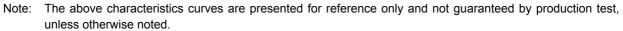








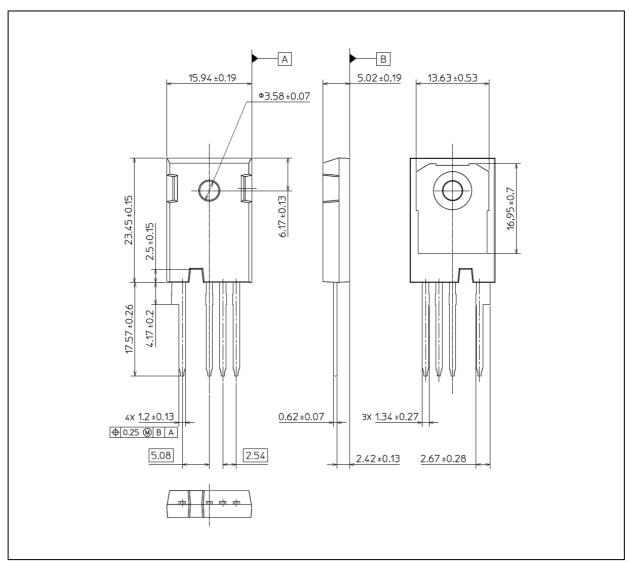




TW083Z65C

Package Dimensions

Unit: mm



Weight: 6.55 g (typ.)

| Package Name(s) |
|------------------------|
| TOSHIBA: 2-16M3A |
| Nickname: TO-247-4L(X) |

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